

ABSTRACT OF THE DISCLOSURE

TITLE OF INVENTION: APPARATUS AND METHOD FOR PRINTING
SOLDER PASTE

A filling squeegee and a scraping squeegee are provided. The filling squeegee is moved in a state without contact with a surface of a mask thereby to fill a solder paste in openings of the mask, then the unnecessary solder paste on the surface of the mask is scraped by the scraping squeegee. The solder paste is prevented from being filled in the openings improperly or scraped improperly even if a speed of the squeegee is increased, so that the solder paste is printed stably on circuit boards.

Figure 1.